

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

SSOP

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TOTAL MASS (g) : 0.327001

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.005806 | 1000000 | 17755.2929688 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.111592 | 962000 | 341258.78125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000000 | 0 | 0 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.003480 | 30000 | 10642.1660156 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000754 | 1500 | 532.108276367 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000174 | 1500 | 532.108276367 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.116000 | 1000000 | 354738.875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.010584 | 1000000 | 32367.1894531 | | |
| | | External Plating Total: | | | | 0.010584 | 1000000 | 32367.1894531 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000928 | 1000000 | 2837.91113281 | | |
| Internal Plating Total: | | | | 0.000928 | 1000000 | 2837.91113281 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001442 | 750000 | 4409.77148438 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000481 | 250000 | 1470.94311523 | | |
| Die Attach Total: | | | | 0.001923 | 1000000 | 5880.71435547 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.025785 | 135000 | 78852.9453125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.164260 | 860000 | 502322.5 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000955 | 5000 | 2920.47949219 | | |
| | | Encapsulation Total: | | | | 0.191000 | 1000000 | 584095.875 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000760 | 1000000 | 2324.15136719 | | |
| | | | | | TOTAL MASS (g) : | 0.327001 | | |